

ABSTRACT OF THE DISCLOSURE

A recessed portion of an adhesive is formed between a wiring board and a heat spreader. Voids occur in the neighborhood of the top of each metal thin wire upon curing an encapsulating resin, thus causing a reduction in moisture resistance. Therefore, the present invention provides a semiconductor device wherein a semiconductor chip and a wiring board are fixed to a heat spreader by an adhesive layer formed over a principal surface of the heat spreader, by using a method such as thermocompression bonding to thereby eliminate a recessed portion, and the parts are sealed with an encapsulating resin inclusive of the semiconductor chip and the metal thin wires.

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